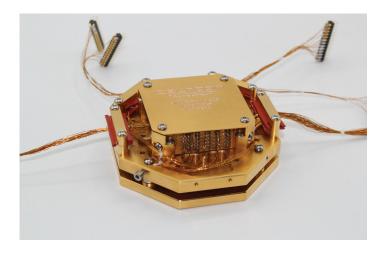


HIGH AND LOW PIN COUNT PROBE CARDS IN STANDARD AND CUSTOM FOOTPRINTS

## **CRYOGENIC APPLICATIONS**

Testing from Ambient to 4K

Over the last 20 years the Celadon Engineering team has developed an expertise in cryogenic materials which has resulted in a solid reputation in the industry for producing extremely stable cryogenic on-wafer probe card as well as DUT probing solutions. These custom cryogenic probe card solutions are widely used to test Space, Military, Medical and Quantum Computing products. Celadon's cryogenic solutions vary from standard VersaTile™ footprints which interface to positioners to innovative custom PCB based designs to allow for flexibility when testing at these very cold temperatures. Lakeshore cryogenic wire is used in standard DC solutions for high density cableout designs to support high pin count applications. During the development process, Celadon works closely with the cryogenic prober vendor to ensure the integrated solution is optimized for current and future testing needs.





## SPECIALIZED CRYOGENIC SPECS

- LakeShore cryogenic wire used in our standard DC footprint for high density cable out for high pin count applications.
- Celadon MobileProbe™ allows for testing of singulated die [post dicing] without full cryogenic probe station.
- The Celadon MobileProbe™ is compatible with Celadon Bamboo™ vertical technology allowing test structure flexibility like never before.
- Celadon pin to pin alignment  $\pm 5\mu m$  in X. Y. and Z.
- -Non-ferromagnetic solutions available.